

**STPS3L60S**

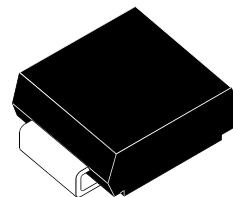
## POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

I <sub>F(AV)</sub>	3 A
V <sub>RRM</sub>	60 V
T <sub>j</sub> (max)	150°C
V <sub>F</sub> (max)	0.65 V

### FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- LOW THERMAL RESISTANCE



**SMC**  
(JEDEC DO-214AB)

### DESCRIPTION

Schottky rectifier suited for Switched Mode Power Supplies and high frequency DC to DC converters. Packaged in SMC, this device is intended for use in DC/DC chargers.

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage	60	V
I <sub>F(RMS)</sub>	RMS forward current	10	A
I <sub>F(AV)</sub>	Average forward current	3	A
I <sub>FSM</sub>	Surge non repetitive forward current	75	A
I <sub>RRM</sub>	Repetitive peak reverse current	1	A
T <sub>stg</sub>	Storage temperature range	- 65 to + 175	°C
T <sub>j</sub>	Maximum operating junction temperature *	150	°C
dV/dt	Critical rate of rise of reverse voltage	10000	V/μs

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$  thermal runaway condition for a diode on its own heatsink

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### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction to leads	20	°C/W

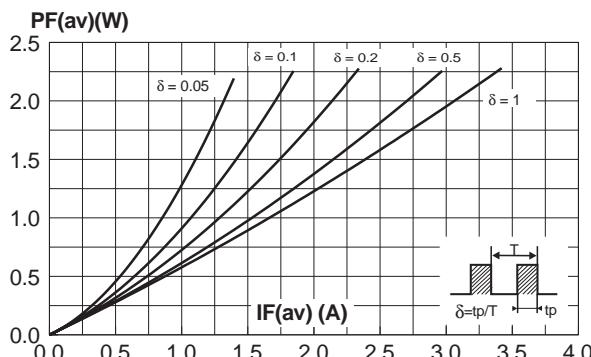
### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$I_R$ *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			55	$\mu\text{A}$
		$T_j = 125^\circ\text{C}$			10	15	mA
$V_F$ *	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 3 \text{ A}$			0.7	V
		$T_j = 125^\circ\text{C}$	$I_F = 3 \text{ A}$		0.56	0.65	
		$T_j = 25^\circ\text{C}$	$I_F = 6 \text{ A}$			0.94	
		$T_j = 125^\circ\text{C}$	$I_F = 6 \text{ A}$		0.67	0.76	

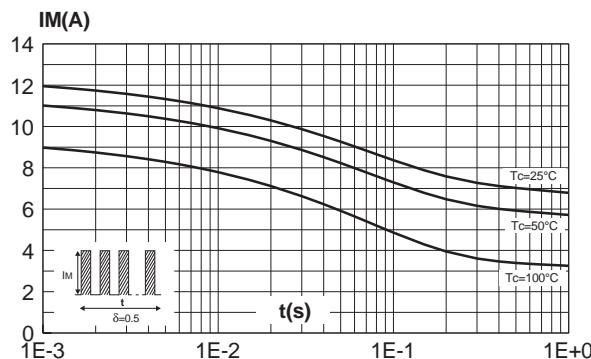
Pulse test : \*  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses use the following equation :  
 $P = 0.54 \times I_F(\text{AV}) + 0.037 I_F^2(\text{RMS})$

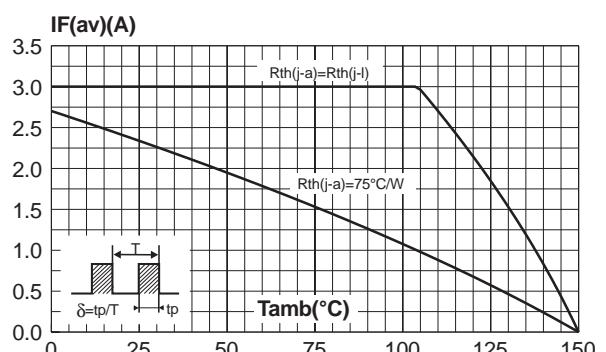
**Fig. 1:** Average forward power dissipation versus average forward current.



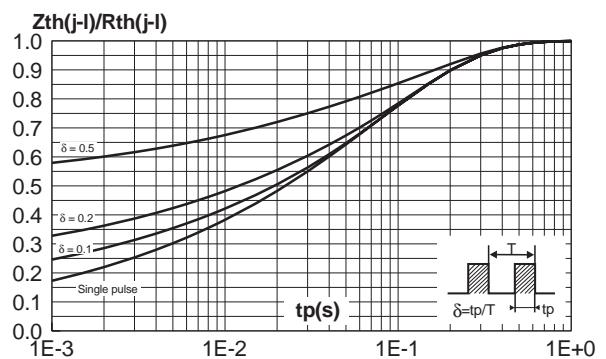
**Fig. 3:** Non repetitive surge peak forward current versus overload duration (maximum values).



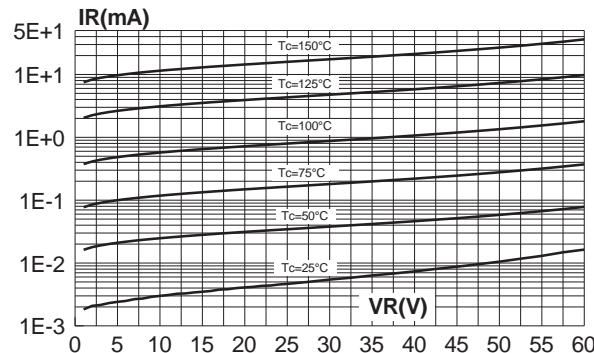
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ ).



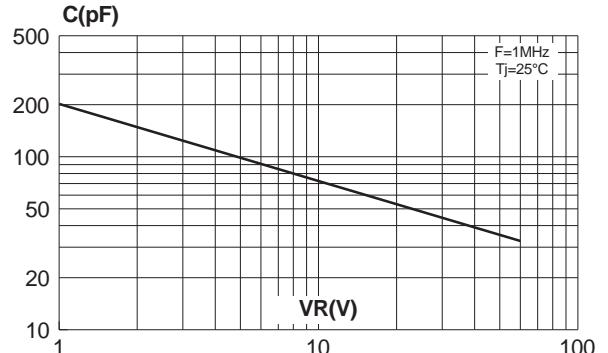
**Fig. 4:** Relative variation of thermal impedance junction to lead versus pulse duration.



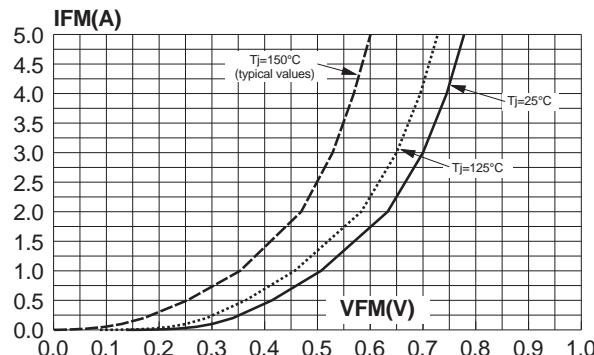
**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values).



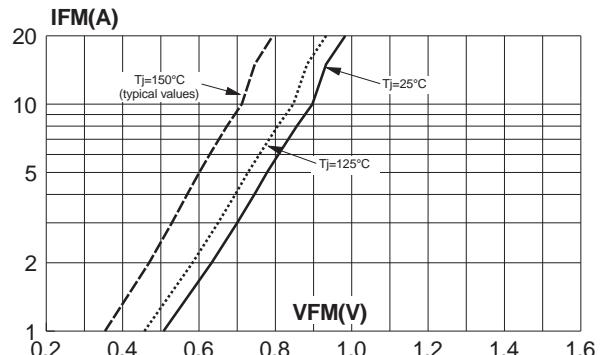
**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values).



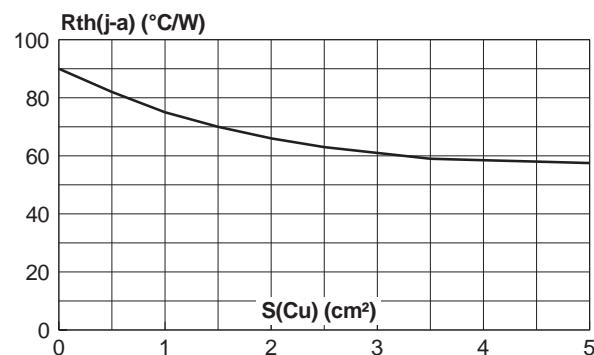
**Fig. 7-1:** Forward voltage drop versus forward current (low level, maximum values).



**Fig. 7-2:** Forward voltage drop versus forward current (high level, maximum values).

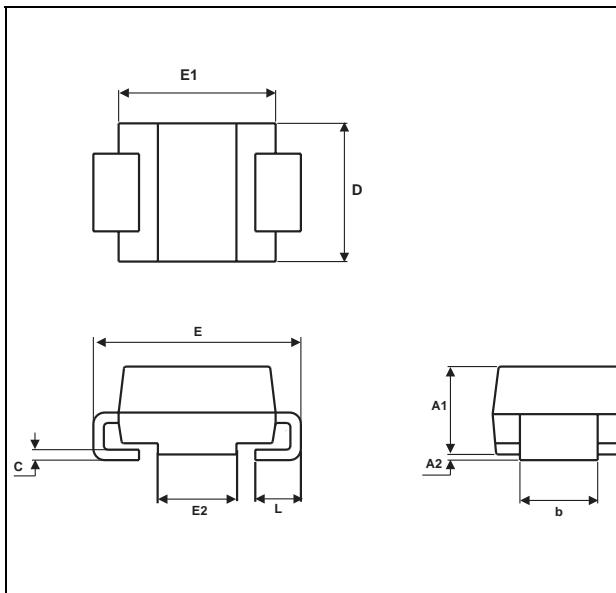


**Fig. 8:** Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: 35mm)



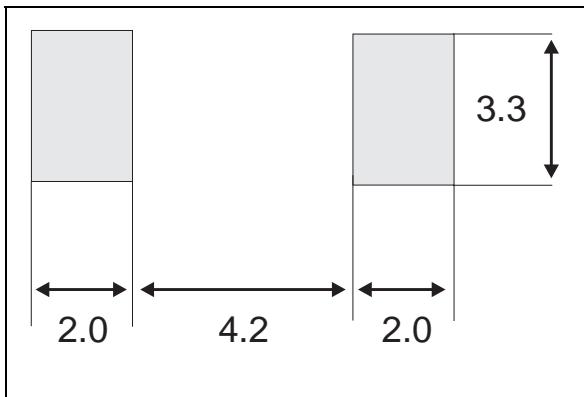
## STPS3L60S

### PACKAGE MECHANICAL DATA SMC



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.2	0.114	0.126
c	0.15	0.41	0.006	0.016
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
D	5.55	6.25	0.218	0.246
L	0.75	1.60	0.030	0.063

### FOOT PRINT ( in millimeters)



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS3L60S	S36	SMC	0.24g	2500	Tape and reel

- Epoxy meets UL94,V0

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